



BOARD'S DRILL SCHEDULE

DRILL SYMBOL	DRILL SIZE	COUNT	PLATED	Tolerance	COMMENT
○	.0098425197	16	YES	---	
⊞	.02	1673	YES	---	
⊕	.041	462	YES	---	
⊞	.042	40	YES	---	
⊖	.047244094	147	YES	---	
⊞	.05	74	YES	---	
⊕	.051181102	24	NO	---	
□	.05511811	75	YES	---	
	.062992126	34	NO	---	
	.07480315	208	YES	---	
	.12	4	YES	---	
	.15	1	NO	---	
	.16535433	52	NO	---	
	.17716535	6	NO	---	

Layer Order - 10 Layer Board

- Film 1 - Top
- Film 2 - Power
- Film 3 - Power
- Film 4 - Power
- Film 5 - Power
- Film 6 - Power
- Film 7 - Power
- Film 8 - Power
- Film 9 - Power
- Film 10 - Bottom

Board Characteristics

0. Material - RF4 - Tg >170C, 0.093" Thick PCB
1. Minimum trace width and clearance: 0.2mm
2. 3 Oz Copper on All Internal Layers; 2 Oz Copper on Top and Bottom
3. Controlled Impedance: 50ohm on 0.2mm wide traces top and bottom
4. Silkscreen on both Sides.
5. Soldermask on Top and Bottom, as per Gerbers
6. Au finish (ENIG) .
7. Minimum 1 mil hole wall copper

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES ARE: FRACTIONS DECIMALS ANGLES .XX .XXX DO NOT SCALE DRAWING			CONTRACT NO.		UNIVERSITY OF CHICAGO ELECTRONICS DEVELOPMENT GROUP TITLE HELIX Relay Board Specification Drawing		
			APPROVALS	DATE			
TREATMENT			DRAWN	M. Bogdan	4/16/2021	SIZE FSCM NO. DWG. NO. 2983 REV. A	
FINISH			CHECKED	M. Bogdan	4/16/2021		
SIMILAR TO			ISSUED			SCALE 1/1 SHEET	
ACT. WT		CALC WT					